

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

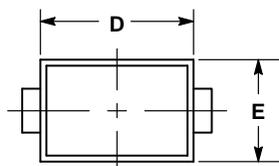
ON Semiconductor®



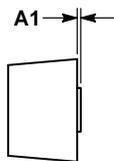
SCALE 2:1

SOD-323FL  
CASE 477AC  
ISSUE B

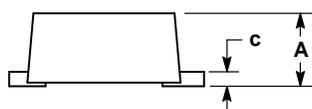
DATE 12 JAN 2016



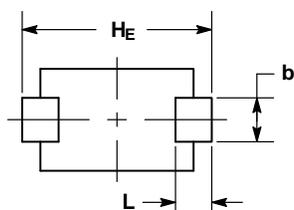
TOP VIEW



END VIEW

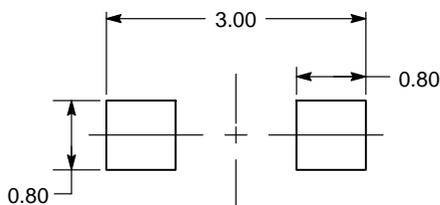


SIDE VIEW



BOTTOM VIEW

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSION: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.08
A1	---	0.10
b	0.50	0.70
c	0.10	0.25
D	2.00	2.20
E	1.30	1.60
HE	2.40	2.80
L	0.35	0.65

### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SOD-323FL	PAGE 1 OF 2

